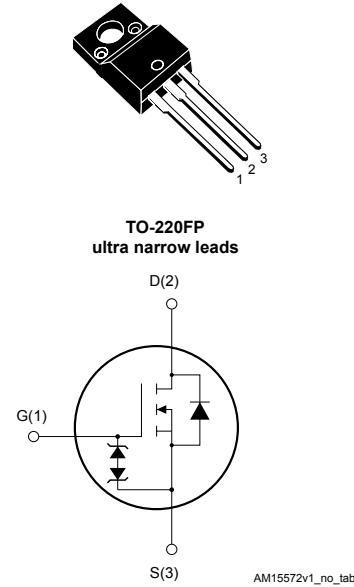


N-channel 650 V, 0.79 Ω typ., 5 A MDmesh M2 Power MOSFET in a TO-220FP ultra narrow leads package

Features



Order code	V_{DS}	$R_{DS(on)\ max.}$	I_D
STFU9N65M2	650 V	0.90 Ω	5 A

- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using MDmesh M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.



Product status link

[STFU9N65M2](#)

Product summary

Order code	STFU9N65M2
Marking	9N65M2
Package	TO-220FP ultra narrow leads
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{GS}	Gate-source voltage	±25	V
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	5	A
I _D ⁽¹⁾	Drain current (continuous) at T _C = 100 °C	3.2	A
I _{DM} ⁽²⁾	Drain current pulsed	20	A
P _{TOT}	Total power dissipation at T _C = 25 °C	20	W
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T _C = 25 °C)	2.5	kV
dv/dt ⁽³⁾	Peak diode recovery voltage slope	15	V/ns
dv/dt ⁽⁴⁾	MOSFET dv/dt ruggedness	50	
T _J	Operating junction temperature range	-55 to 150	°C
T _{stg}	Storage temperature range		

1. Current limited by package.
2. Pulse width limited by safe operating area.
3. I_{SD} ≤ 5 A, di/dt ≤ 400 A/μs, V_{DS(peak)} ≤ V_{(BR)DSS}, V_{DD} = 400 V.
4. V_{DS} ≤ 520 V.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	6.25	°C/W
R _{thj-amb}	Thermal resistance junction-ambient	62.5	°C/W

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T _J max)	1	A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	105	mJ

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	650			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}$			1	μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}, T_C = 125^\circ\text{C}$ ⁽¹⁾			100	μA
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$		0.79	0.90	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	310	-	pF
C_{oss}	Output capacitance		-	18	-	pF
C_{rss}	Reverse transfer capacitance		-	0.9	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent capacitance energy related	$V_{DS} = 0 \text{ to } 520 \text{ V}, V_{GS} = 0 \text{ V}$	-	109	-	pF
R_g	Intrinsic gate resistance	$f = 1 \text{ MHz}$ open drain	-	6.6	-	Ω
Q_g	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 5 \text{ A}$ $V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	10.3	-	nC
Q_{gs}	Gate-source charge		-	2.4	-	nC
Q_{gd}	Gate-drain charge		-	4.8	-	nC

1. $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325 \text{ V}, I_D = 2.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	7.5	-	ns
t_r	Rise time		-	6.6	-	ns
$t_{d(off)}$	Turn-off delay time		-	22.5	-	ns
t_f	Fall time		-	18	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		20	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 5 \text{ A}, V_{DD} = 60 \text{ V}$	-	276		ns
Q_{rr}	Reverse recovery charge	$dI/dt = 100 \text{ A}/\mu\text{s}$	-	1.7		μC
I_{RRM}	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	12.5		A
t_{rr}	Reverse recovery time	$I_{SD} = 5 \text{ A}, V_{DD} = 60 \text{ V}$	-	312		ns
Q_{rr}	Reverse recovery charge	$dI/dt = 100 \text{ A}/\mu\text{s}, T_J = 150 \text{ }^\circ\text{C}$	-	1.9		μC
I_{RRM}	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	12.4		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5 %.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

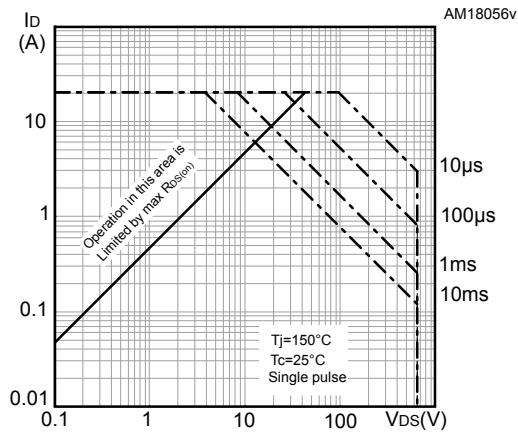


Figure 2. Thermal Impedance

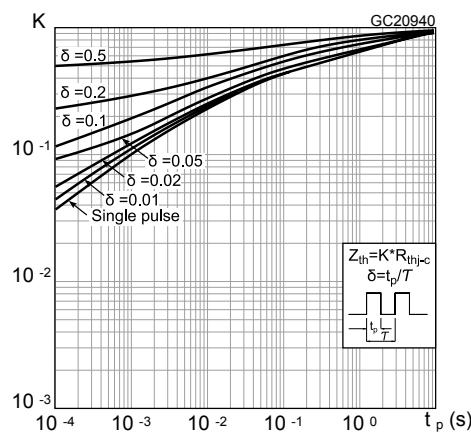


Figure 3. Output characteristics

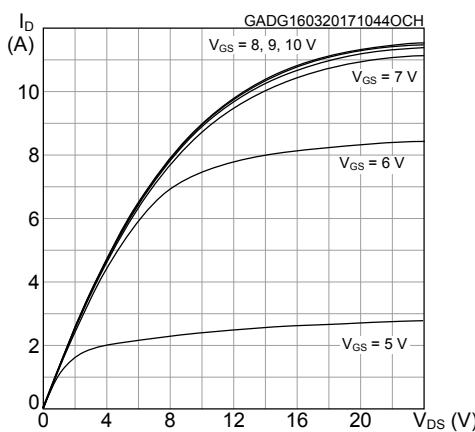


Figure 4. Transfer characteristics

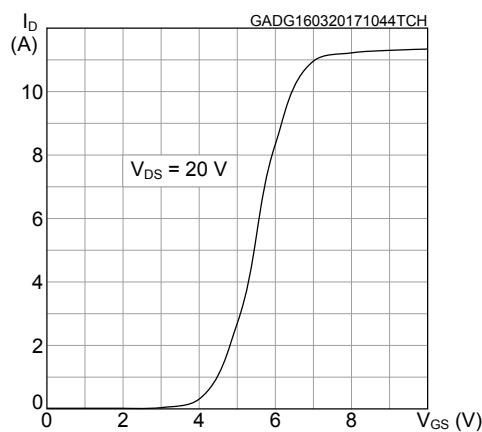


Figure 5. Gate charge vs gate-source voltage

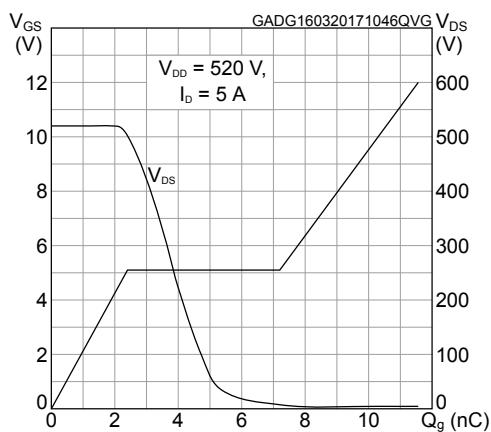


Figure 6. Static drain-source on-resistance

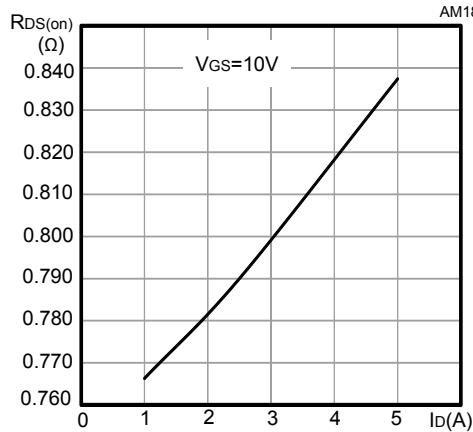
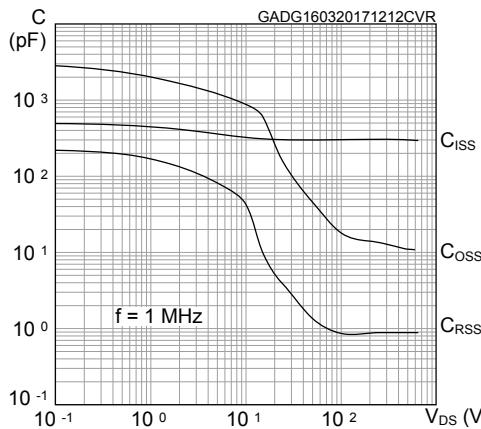
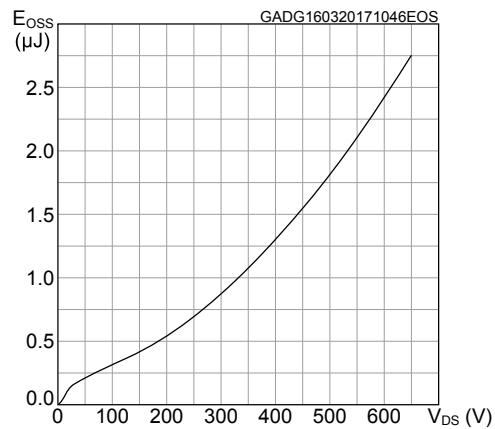
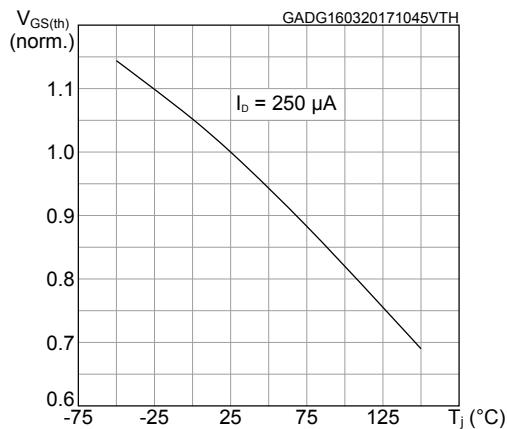
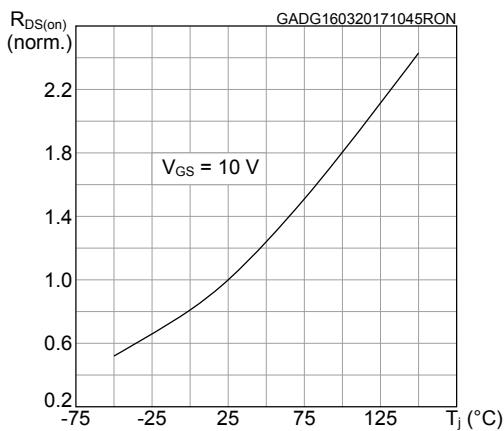
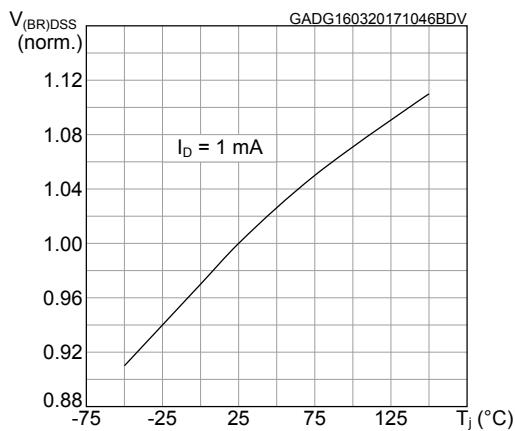
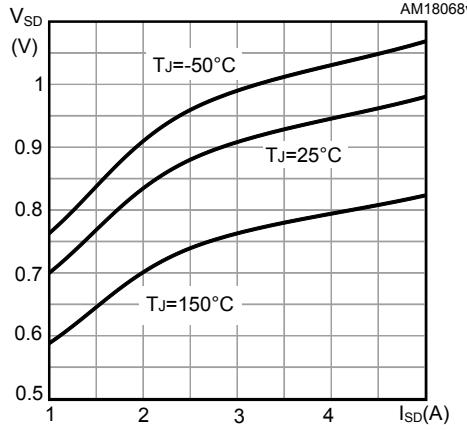
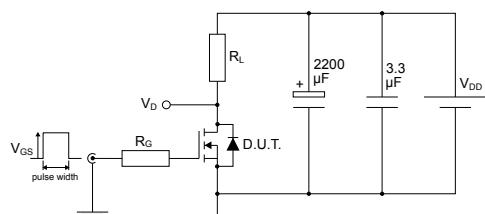


Figure 7. Capacitance variations

Figure 8. Output capacitance stored energy

Figure 9. Normalized gate threshold voltage vs temperature

Figure 10. Normalized on-resistance vs temperature

Figure 11. Normalized V(BR)DSS vs temperature

Figure 12. Source-drain diode forward characteristics


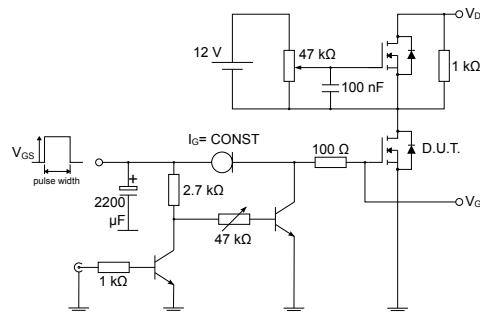
3 Test circuits

Figure 13. Test circuit for resistive load switching times



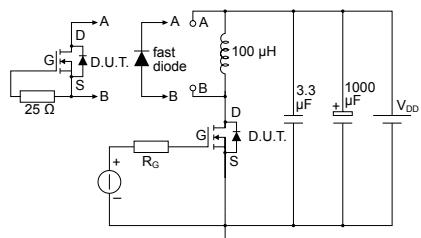
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Figure 14. Test circuit for gate charge behavior



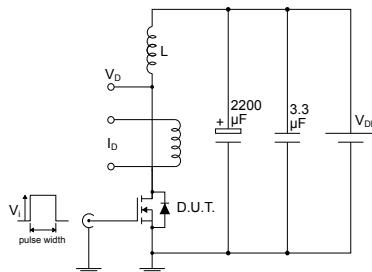
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Figure 15. Test circuit for inductive load switching and diode recovery times



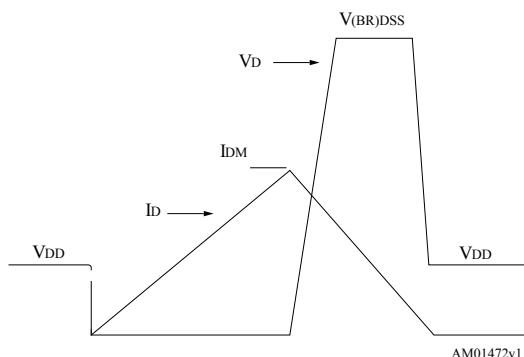
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Figure 16. Unclamped inductive load test circuit



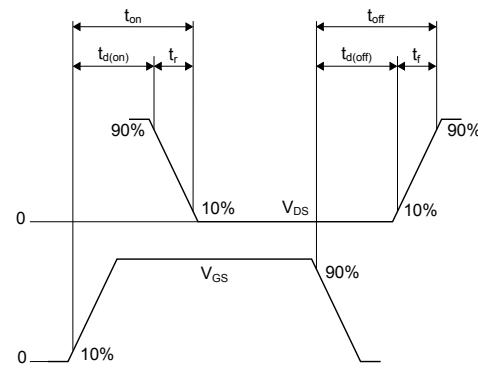
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Figure 17. Unclamped inductive waveform



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Figure 18. Switching time waveform



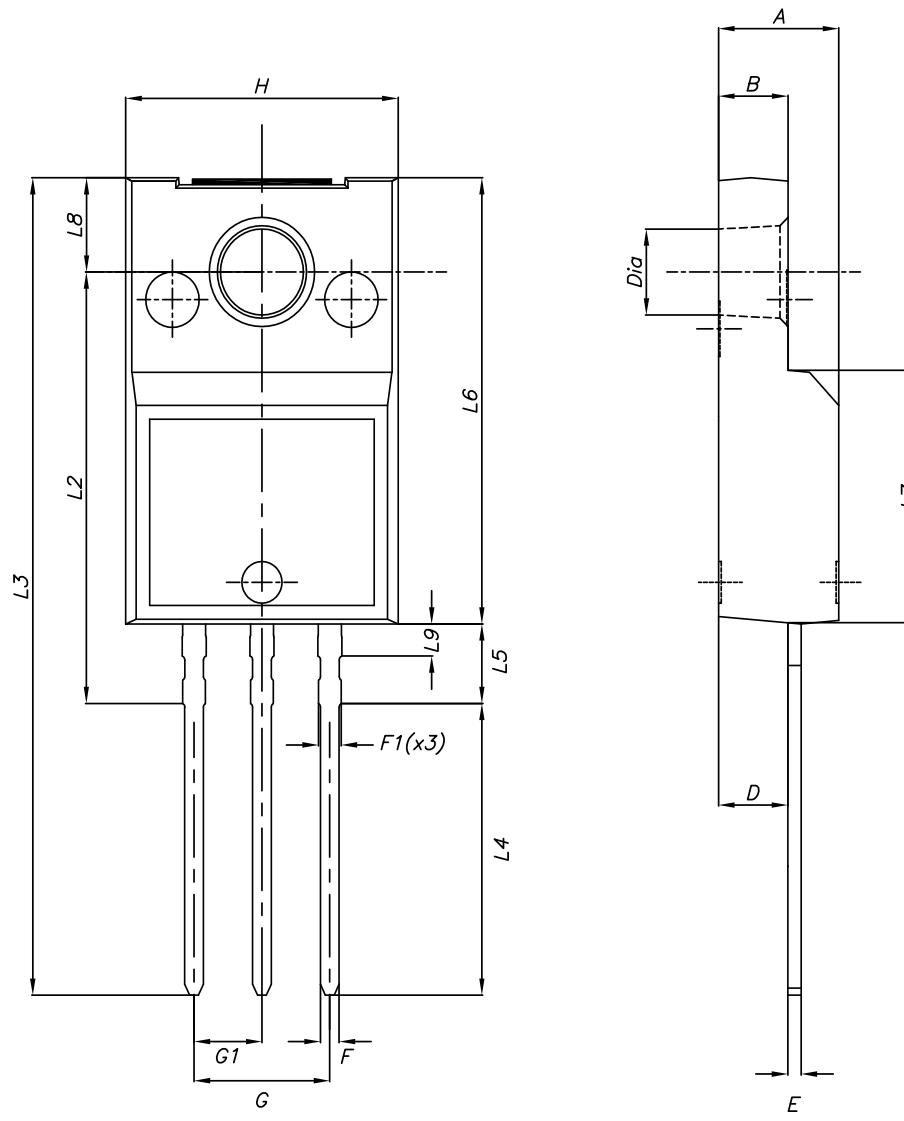
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-220FP ultra narrow leads package information

Figure 19. TO-220FP ultra narrow leads package outline



8576148_2

Table 8. TO-220FP ultra narrow leads mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.60
F	0.65		0.75
F1	-		0.90
G	4.95		5.20
G1	2.40	2.54	2.70
H	10.00		10.40
L2	15.10		15.90
L3	28.50		30.50
L4	10.20		11.00
L5	2.50		3.10
L6	15.60		16.40
L7	9.00		9.30
L8	3.20		3.60
L9	-		1.30
Dia.	3.00		3.20

Revision history

Table 9. Document revision history

Date	Revision	Changes
04-Aug-2016	1	First release.
08-Sep-2016	2	Document status updated from preliminary to production data.
21-Jun-2019	3	Updated Table 1. Absolute maximum ratings and Table 5. Dynamic . Updated Section 2.1 Electrical characteristics (curves) . Minor text changes.

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